

IN THE CLAIMS:

Claims 1 through 37, 44, 53 through 59 and 70 through 74 were previously cancelled. Claims 38, 39, 52 and 60 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1.-37. (Cancelled)

38. (Currently amended) A semiconductor device, comprising:
a semiconductor device having contact pads exposed at a surface thereof, the contact pads being arranged in at least one substantially linear relationship positioned at or proximate a centerline of the semiconductor device and being configured to communicate with corresponding test pads of a test substrate, from which the semiconductor device is detachable, upon disposing the semiconductor device face-down over the test substrate;
and
at least one stabilizer secured to and protruding from the surface of the semiconductor device, the at least one stabilizer being configured to at least partially stabilize an orientation of the semiconductor device upon disposal thereof face-down over the test substrate and including a plurality of superimposed, contiguous, mutually adhered layers of the same material.

39. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer protrudes from the surface at most a distance between a plane of the surface of the semiconductor device and a plane of a surface of the test substrate upon disposing the semiconductor device face-down over the test substrate.

40. (Previously presented) The semiconductor device of claim 39, wherein the at least one stabilizer protrudes from the surface at most the distance between the plane of the surface of the semiconductor device and the plane of the surface of the test substrate when at least one conductor connects at least one of the contact pads and a corresponding one of the test pads.

41. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer comprises a dielectric material.

42. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer comprises a photopolymer.

43. (Previously presented) The semiconductor device of claim 42, wherein the photopolymer is at least semisolid.

44. (Cancelled)

45. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer is positioned to be located proximate a corner of the surface.

46. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer is positioned to be located proximate an edge of the surface.

47. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer has a cross-sectional plan of one of quadrilateral, round, oval, and triangular.

48. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer is elongated in a direction parallel to a plane in which the semiconductor device is located.

49. (Previously presented) The semiconductor device of claim 38, wherein the semiconductor device comprises a semiconductor wafer.

50. (Previously presented) The semiconductor device of claim 38, wherein the semiconductor device comprises a semiconductor die.

51. (Previously presented) The semiconductor device of claim 38, wherein the semiconductor device comprises a chip-scale package.

52. (Currently amended) The semiconductor device of claim 38, wherein the test substrate also includes at least one stabilizer configured to at least partially stabilize the test substrate upon disposing the semiconductor device face-down over the test substrate.

53.-59. (Cancelled)

60. (Currently amended) An assembly of a semiconductor device and a test substrate, comprising:

a test substrate with a plurality of test pads exposed at a surface thereof and arranged in at least one substantially linear relationship;

a semiconductor device with a plurality of contact pads exposed at a surface thereof, the plurality of contact pads being arranged in at least one substantially linear relationship which is located at or proximate a centerline of the semiconductor device, the surface of the semiconductor device detachably assembled with and facing the surface of the test substrate with the plurality of contact pads in temporary communication with corresponding test pads of the plurality of test pads; and

at least one stabilizer secured to a surface of the semiconductor device and disposed between the test substrate and the semiconductor device.

61. (Previously presented) The assembly of claim 60, wherein the at least one stabilizer is secured to the surface of the test substrate.

62. (Previously presented) The assembly of claim 60, wherein the at least one stabilizer is secured to the surface of the semiconductor device.

63. (Previously presented) The assembly of claim 60, comprising a plurality of stabilizers, at least one of the plurality of stabilizers being secured to the surface of the test substrate and at least one other of the plurality of stabilizers being secured to the surface of the semiconductor device.

64. (Previously presented) The assembly of claim 60, wherein the at least one stabilizer comprises a photopolymer.

65. (Previously presented) The assembly of claim 60, wherein the photopolymer is at least semisolid.

66. (Previously presented) The assembly of claim 64, wherein the at least one stabilizer has a plurality of adjacent, mutually adhered regions.

67. (Previously presented) The assembly of claim 60, wherein the at least one stabilizer extends between a plane of the surface of the test substrate and a plane of the surface of the semiconductor device at most a distance between the planes of the surfaces upon establishing communication between the plurality of contact pads and the corresponding test pads.

68. (Previously presented) The assembly of claim 60, further comprising at least one conductive structure disposed between the test substrate and the semiconductor device.

69. (Previously presented) The assembly of claim 68, wherein the at least one stabilizer extends between a plane of the surface of the test substrate and a plane of the surface of the semiconductor device at most a distance the at least one conductive structure extends between the planes of the surfaces.

70.-74. (Cancelled)